

MDTE Series

Wire Wound Molded SMD Power Inductors Size 7030



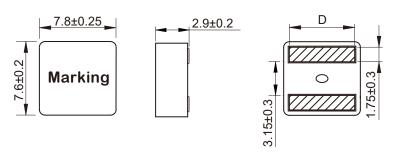
FEATURES

- Soft saturation
- High current,low DCR,high efficiency
- Very low acoustic noise and very low leakage flux noise
- High reliability
- 100% Lead(Pb)-Free and RoHS compliant
- Operating temperature -55~+125 °C (Including self temperature rise)
- Quantity: 1500pcs

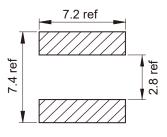
APPLICATION

- Note PC power system,incl. IMVP-6
- DC/DC converter

Dimensions: [mm]







Electrical Properties:

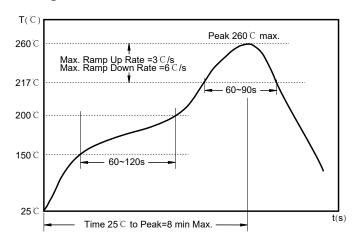
Part No	Inductance @ 100KHz/0.1V (μΗ)	Tolerance	Saturation Current Typ. (A)	Saturation Current Max. (A)	Temperature Rise Current Typ. (A)	DC Resistance Max. (mΩ)	D (mm)
MDTE7030-1R0M	1.00	±20%	30.0	28.0	21.8	5.00	6.6±0.3
MDTE7030-1R5M	1.50	±20%	25.0	23.5	15.3	8.25	6.6±0.3
MDTE7030-2R2M	2.20	±20%	19.0	17.0	13.0	13.7	6.2±0.3
MDTE7030-2R7M	2.70	±20%	16.0	13.5	11.4	15.4	6.2±0.3
MDTE7030-3R3M	3.30	±20%	15.0	13.0	10.0	18.0	6.2±0.3
MDTE7030-4R7M	4.70	±20%	13.5	12.2	9.00	26.7	6.2±0.3
MDTE7030-5R6M	5.60	±20%	12.5	11.5	7.30	33.2	6.2±0.3
MDTE7030-6R8M	6.80	±20%	12.0	11.0	6.80	42.5	6.2±0.3
MDTE7030-8R2M	8.20	±20%	10.2	9.0	5.90	48.73	6.2±0.3

Saturation Current will cause L to drop approximately 30%

Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40°C



Soldering Reflow:



Preheat condition: 150 ~200 °C / 60~120 sec.

Allowed time above 217 °C: 60~90 sec.

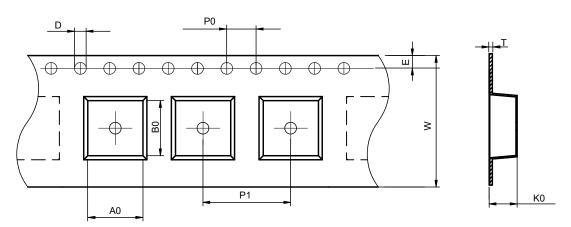
Max temperature: 260 ℃.

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

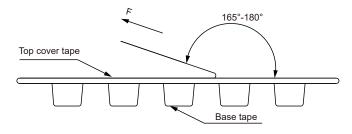
Packaging Information:

Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTE7030	8.2±0.1	8.0±0.1	1.5±0.1	4.0±0.1	12.0±0.1	16.0±0.3	3.3±0.1	1.75±0.1	0.35±0.05

Peel force of top cover tape:

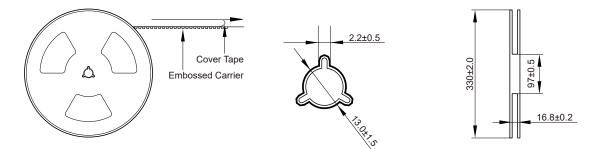


The peel force of top cover tape shall be between 0.1 to 1.3 N

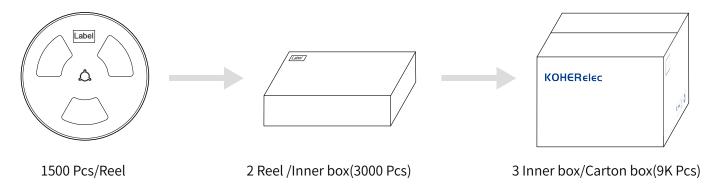
Product Marking:



Reel Dimension: [mm]



Packaging Quantity:



Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer
 does.As a result customer shall be responsible for checking and confirming whether Koher product with the
 performance described in the product specification is suitable for using in customer's particular application or
 not.